



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!






Contact us


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APPLICABLE STANDARD		STORAGE TEMPERATURE RANGE		
RATING	OPERATING TEMPERATURE RANGE -40°C T0 + 85°C (NOTE 1) 	STORAGE TEMPERATURE RANGE -10°C T0 + 60°C (NOTE 2)		
OPERATING HUMIDITY RANGE	40% T0 + 80%	STORAGE HUMIDITY RANGE	40% T0 + 70% (NOTE 2)	
	VOLTAGE	250V AC	VOLTAGE	
	CURRENT	AWG 22 T0 26 : 2A AWG 28 : 1A AWG 30 : 0.5A	UL • CSA RATING CURRENT	AWG 22 : 2A AWG 24 T0 28 : 1A AWG 30 : 0.5A
SPECIFICATIONS				
ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	X	X
MARKING	CONFIRMED VISUALLY.		X	X
ELECTRIC CHARACTERISTICS				
CONTACT RESISTANCE	100mA (DC OR 1000 Hz).	30mΩ MAX.	X	—
INSULATION RESISTANCE	500V DC.	1000MΩ MIN.	X	—
VOLTAGE PROOF	650V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	—
MECHANICAL CHARACTERISTICS				
MECHANICAL OPERATION	30 TIMES INSERTIONS AND EXTRACTATIONS.	① CONTACT RESISTANCE: 30mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		X	—
ENVIRONMENTAL CHARACTERISTICS				
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55→-5 TO 35→+85 →-5 TO 35 °C TIME 30→5 TO 15 →30 →5 TO 15 min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 1000MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.	① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
 1	DIS-H-008540	MI. SAKIMURA	HK. UMEHARA	14. 02. 26
		APPROVED	TY. OMA	06. 04. 06
		CHECKED	HK. UMEHARA	06. 04. 06
		DESIGNED	NS. HIROSE	06. 04. 06
		DRAWN	AK. MIURA	06. 02. 22
Note QT:Qualification Test AT:Assurance Test X:Applicable Test		DRAWING NO.	ELC4-307176-02	
HRS				
SPECIFICATION SHEET		PART NO.	DF11GZ-*DP-2V (27)	
HIROSE ELECTRIC CO., LTD.		CODE NO.	CL543	 1/2

SPECIFICATIONS						
ITEM	TEST METHOD	REQUIREMENTS	QT	AT		
RESISTANCE TO SOLDERING HEAT	1) AUTOMATIC SOLDERING (REFLOW)《REFLOW AREA》MAX 250℃ WITHIN 10 sec. MIN 230℃ WITHIN 60 sec.《PREHEATING AREA》150 TO 180℃ 90 TO 120 sec. PUT THROUGH IN REFROW FUMACE TWICE. FEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNEVCTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :290 ± 10℃, SOLDERING TIME :3s. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	—		
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE. 230±5℃ FOR IN IMMERSION , DURATION, 3 s.	A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	X	—		
REMARKS						
NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE 2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD , AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION. NOTE 3:THE TEMPERATURE PROFILE SHALL BE APPLIED WITHIN 168 HOURS AFTER OPENING MOISTURE-PROOF PACKAGING. WHEN 168 HOURS PASSED AFTER OPENING , APPLY THE BOTTOM REQUIREMENTS. 《REFLOW AREA》 MAX 240℃ WITHIN 10 sec. MIN 230℃ WITHIN 60 sec. 《PREHEATING AREA》 150 TO 180℃ 90 TO 120 s.						
Unless otherwise specifid , refer to IEC 60512.						
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